

FluxPlus™ Paste Flux

Flux characteristics are the most important feature when dispensing and reflowing solder paste. We provide a wide array of formulations available in No Clean (NC), Water Soluble (WS), Rosin Mildly Activated (RMA), and Rosin Activated (RA) to suit your application needs. We supply fluxes formulated to work with any alloy and heating process, perfect for rework and BGA applications.

No Clean (NC)

Consists of rosin, solvent, and a small amount of activator. NC flux has low activity and is suited to easily solderable surfaces. NC residue is clear, hard, noncorrosive, non-conductive, and designed to be left on your assembly. Residue may be removed with an appropriate solvent.

Water Soluble (WS)

Consists of organic acids, thixotrope, and solvent. WS flux comes in a wide range of activity levels for soldering to even the most difficult surfaces. WS flux residue is corrosive and should be removed as soon as possible after reflow to avoid damage to your assembly. Maximum safe time before cleaning is product dependent. Residue is easily removed with 60°C (140°F) water at 40 psi pressure.

Rosin Mildly Activated (RMA)

Consists of rosin, solvent, and a small amount of activator. Most RMA flux is fairly low in activity and best suited to easily solderable surfaces. RMA flux residue is clear, soft, non-corrosive, and non-conductive. Cleaning is optional. Residue may be removed with an appropriate solvent.

Rosin Activated (RA)

Consists of rosin, solvent, and aggressive activators. RA flux has higher activity than RMA for moderately oxidized surfaces. RA flux residue is corrosive and should be removed as soon as possible after reflow to prevent damage to your assembly. Maximum safe time before cleaning is product dependent. Residue may be removed with an appropriate solvent.